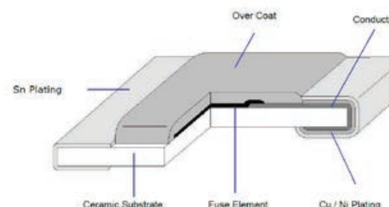
MATERIAL DECLARATION SHEET

Material Number	SF-0603SP	
Product Line	Lead Free Thin Film Chip Fuse	
Compliance Date	2017/07/05	
RoHS Compliant	Yes	MSL



No.	Construction Element (subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ceramic Substrate	Ceramic	0.00104973068	Aluminum oxide	1344-28-1	96%	78.90%	82.19%
				Quartz	14808-60-7	3%	2.47%	
				Magnesium oxide	1309-48-4	1%	0.82%	
2	Inner Conductor	Titanium - Tungsten	0.00000817408	Titanium	7440-32-6	13.5%	0.09%	0.64%
				Tungsten	7440-33-7	1.5%	0.01%	
		Copper		Copper	7440-50-8	85%	0.54%	
3	Isolation	Quartz	0.00001060076	Quartz	14808-60-7	100%	0.83%	0.83%
4	Fuse Element	Copper	0.00000664144	Copper	7440-50-8	90%	0.47%	0.52%
		Tin		Tin	7440-31-5	10%	0.05%	
5	Over-Coating	Epoxy	0.00004738412	Epoxy	29690-82-2	100%	3.71%	3.71%
6	End Terminal	Nickel - Chromium	0.00000166036	Nickel	7440-02-0	80%	0.10%	0.13%
				Chromium	7440-47-3	20%	0.03%	
7	Marking	Epoxy	0.00000191580	Epoxy	25085-99-8	100%	0.15%	0.15%
8	Cu Plating	Copper	0.00006718072	Copper	7440-50-8	100%	5.26%	5.26%
9	Ni Plating	Nickel	0.00004431884	Nickel	7440-02-0	100%	3.47%	3.47%
10	Sn plating	Tin	0.00003959320	Tin	7440-31-5	100%	3.10%	3.10%
		TOTAL WEIGHT	0.0012772					

This Document was updated on: 4-25-2018

CASRN: CAS Registry Number® is a Registered Trademark of the American Chemical Society